AMENDMENTS TO THE CLAIMS

Please amend the claims as follows. Please cancel claims 30-44 without prejudice or disclaimer. Please add new claims 45-59.

1-44. (Canceled).

45. (New) An integrated circuit structure comprising:

a substrate having an upper surface, wherein said substrate comprises a substrate material;

an opening in said upper surface of said substrate defined by said substrate material;

a second surface parallel to and at a depth less than said upper surface;

a third surface parallel to and at a second depth less than said second surface;

a first vertical wall substantially orthogonal to and intersecting said upper surface at said opening and said second surface;

a second vertical wall substantially orthogonal to and intersecting said second and said third surfaces; and

a conductor filling said opening,

wherein said second vertical wall is positioned in a vertical direction within a horizontal dimension of said opening.

46. (New) The integrated circuit structure according to claim 45, wherein a face said second surface is positioned in an upward direction.

47. (New) The integrated circuit structure according to claim 45, wherein corresponding first and second vertical walls are symmetrically disposed from said first and second vertical walls on an opposite side of a centerline of said opening.

48. (New) The integrated circuit structure according to claim 45, wherein said upper, second and third surfaces each intersect their respective first and second vertical walls at substantially right angles.

49. (New) The integrated circuit structure according to claim 45, wherein an intersection of said second vertical wall and said second surface is coplanar in a horizontal direction with an intersection of said second vertical wall and said third surface.

50. (New) An integrated circuit structure comprising:

a substrate having an upper surface, wherein said substrate comprises a substrate material;

an opening in said upper surface of said substrate defined by said substrate material;

a second surface parallel to and at a depth less than said upper surface;

a third surface parallel to and at second depth less than said second surface;

a fourth surface parallel to and at a third depth less than said third surface;

a first vertical wall substantially orthogonal to and intersecting said upper surface at said opening and said second surface;

a second vertical wall substantially orthogonal to and intersecting said second and said third surfaces;

a third vertical wall substantially orthogonal to and intersecting said third and fourth

surfaces; and

a conductor filling said opening,

wherein said second vertical wall is positioned in a vertical direction within a horizontal dimension of said opening, and

wherein said third vertical wall is positioned vertically between a horizontal dimension of said opening and said second vertical wall.

51. (New) The integrated circuit structure according to claim 50, wherein a face said second and fourth surfaces are positioned in an upward direction.

52. (New) The integrated circuit structure according to claim 50, wherein a face said third surface is positioned in a downward direction.

53. (New) The integrated circuit structure according to claim 50, wherein corresponding first, second and third vertical walls are symmetrically disposed from said first and second vertical walls on an opposite side of a centerline of said opening.

54. (New) The integrated circuit structure according to claim 50, wherein said upper, second, third and fourth surfaces each intersect their respective first, second and third vertical walls at substantially right angles.

55. (New) An integrated circuit structure comprising:

a substrate having an upper surface, wherein said substrate comprises a substrate material;

an opening in said upper surface of said substrate defined by said substrate material;

a second surface parallel to and at a depth less than said upper surface;

a third surface parallel to and at a second depth less than said second surface;

a first vertical wall substantially orthogonal to and intersecting said upper surface at said opening and said second surface;

a second vertical wall substantially orthogonal to and intersecting said second and said third surfaces; and

a conductor filling said opening, and

wherein said second vertical wall is positioned in a vertical direction within a horizontal dimension of said opening.

56. (New) The integrated circuit structure according to claim 55, wherein a face said second surface is positioned in a downward direction.

57. (New) The integrated circuit structure according to claim 55, wherein corresponding first and second vertical walls are symmetrically disposed from said first and second vertical walls on an opposite side of a centerline of said opening.

58. (New) The integrated circuit structure according to claim 55, wherein said upper, second and third surfaces each intersect their respective first and second vertical walls at substantially right angles.

59. (New) The integrated circuit structure according to claim 55, wherein an

intersection of said second vertical wall and said second surface is coplanar in a horizontal direction with an intersection of said second vertical wall and said third surface.